

**REPETITIVE AVALANCHE AND dv/dt RATED  
HEXFET® TRANSISTORS  
THRU-HOLE - TO-205AF (TO-39)**

**IRFF9120  
JANTX2N6845  
JANTXV2N6845  
REF:MIL-PRF-19500/563  
100V, P-CHANNEL**

**Product Summary**

Part Number	BVDSS	R <sub>Ds(on)</sub>	I <sub>D</sub>
IRFF9120	-100V	0.60Ω	-4.0A

The HEXFET® technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry and unique processing of this latest "State of the Art" design achieves: very low on-state resistance combined with high transconductance.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high energy pulse circuits.



**Features:**

- Repetitive Avalanche Ratings
- Dynamic dv/dt Rating
- Hermetically Sealed
- Simple Drive Requirements
- Ease of Parallelizing
- ESD Rating: Class 1B per MIL-STD-750, Method 1020

**Absolute Maximum Ratings**

	Parameter		Units
I <sub>D</sub> @ V <sub>GS</sub> = -10V, T <sub>C</sub> = 25°C	Continuous Drain Current	-4.0	A
I <sub>D</sub> @ V <sub>GS</sub> = -10V, T <sub>C</sub> = 100°C	Continuous Drain Current	-2.6	
I <sub>DM</sub>	Pulsed Drain Current ①	-16	
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	20	W
	Linear Derating Factor	0.16	W/°C
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	364	mJ
I <sub>AR</sub>	Avalanche Current ①	-4.0	A
EAR	Repetitive Avalanche Energy ①	2.0	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
T <sub>J</sub> T <sub>TSG</sub>	Operating Junction Storage Temperature Range	-55 to 150	°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)	
	Weight	0.98(typical)	g

For footnotes refer to the last page

**Electrical Characteristics @  $T_j = 25^\circ\text{C}$  (Unless Otherwise Specified)**

	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{BV}_{\text{DSS}}$	Drain-to-Source Breakdown Voltage	-100	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_D = -1.0\text{mA}$
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Temperature Coefficient of Breakdown Voltage	—	-0.10	—	$\text{V}/^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $\text{I}_D = -1.0\text{mA}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source On-State Resistance	—	—	0.60	$\Omega$	$\text{V}_{\text{GS}} = -10\text{V}$ , $\text{I}_D = -2.6\text{A}$ ④
		—	—	0.69		$\text{V}_{\text{GS}} = -10\text{V}$ , $\text{I}_D = -4.0\text{A}$ ④
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$ , $\text{I}_D = -250\mu\text{A}$
$\text{g}_{\text{fs}}$	Forward Transconductance	1.25	—	—	S	$\text{V}_{\text{DS}} = -15\text{V}$ , $\text{I}_{\text{DS}} = -2.6\text{A}$ ④
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	—	—	-25	$\mu\text{A}$	$\text{V}_{\text{DS}} = -80\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$
		—	—	-250		$\text{V}_{\text{DS}} = -80\text{V}$ $\text{V}_{\text{GS}} = 0\text{V}$ , $T_j = 125^\circ\text{C}$
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Forward	—	—	-100	nA	$\text{V}_{\text{GS}} = -20\text{V}$
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Reverse	—	—	100		$\text{V}_{\text{GS}} = 20\text{V}$
$\text{Q}_g$	Total Gate Charge	4.3	—	16.3	nC	$\text{V}_{\text{GS}} = -10\text{V}$ , $\text{I}_D = -4.0\text{A}$
$\text{Q}_{\text{gs}}$	Gate-to-Source Charge	1.3	—	4.7		$\text{V}_{\text{DS}} = -50\text{V}$
$\text{Q}_{\text{gd}}$	Gate-to-Drain ('Miller') Charge	1.0	—	9.0	ns	$\text{V}_{\text{DD}} = -50\text{V}$ , $\text{I}_D = -4.0\text{A}$ , $\text{V}_{\text{GS}} = -10\text{V}$ , $\text{R}_G = 7.5\Omega$
$t_{\text{d(on)}}$	Turn-On Delay Time	—	—	60		
$t_r$	Rise Time	—	—	100		
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	—	50		
$t_f$	Fall Time	—	—	70	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
$\text{L}_{\text{S}} + \text{L}_{\text{D}}$	Total Inductance	—	7.0	—		
$\text{C}_{\text{iss}}$	Input Capacitance	—	380	—	pF	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{V}_{\text{DS}} = -25\text{V}$ $f = 1.0\text{MHz}$
$\text{C}_{\text{oss}}$	Output Capacitance	—	170	—		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance	—	45	—		

**Source-Drain Diode Ratings and Characteristics**

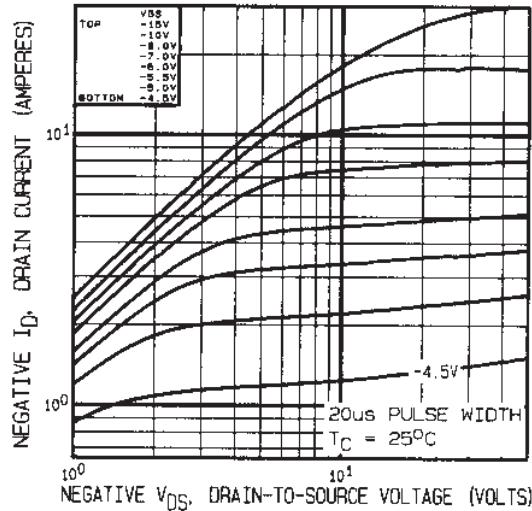
	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{I}_S$	Continuous Source Current (Body Diode)	—	—	-4.0	A	
$\text{ISM}$	Pulse Source Current (Body Diode) ①	—	—	-16		
$\text{V}_{\text{SD}}$	Diode Forward Voltage	—	—	-4.8	V	$T_j = 25^\circ\text{C}$ , $\text{I}_S = -4.0\text{A}$ , $\text{V}_{\text{GS}} = 0\text{V}$ ④
$\text{t}_{\text{rr}}$	Reverse Recovery Time	—	—	200	ns	$T_j = 25^\circ\text{C}$ , $\text{I}_F = -4.0\text{A}$ , $d\text{i}/dt \leq -100\text{A}/\mu\text{s}$
$\text{QRR}$	Reverse Recovery Charge	—	—	3.1	$\mu\text{C}$	$\text{V}_{\text{DD}} \leq -50\text{V}$ ④
$t_{\text{on}}$	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_{\text{S}} + \text{L}_{\text{D}}$ .				

**Thermal Resistance**

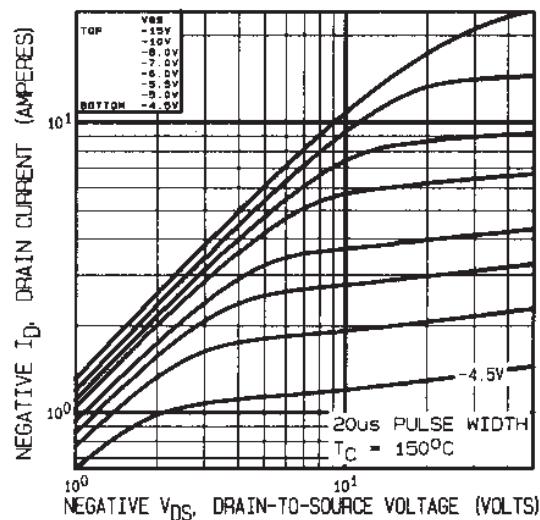
	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{R}_{\text{thJC}}$	Junction-to-Case	—	—	6.25	$^\circ\text{C/W}$	
$\text{R}_{\text{thJA}}$	Junction-to-Ambient	—	—	175		Typical socket mount

**Note:** Corresponding Spice and Saber models are available on International Rectifier Website.

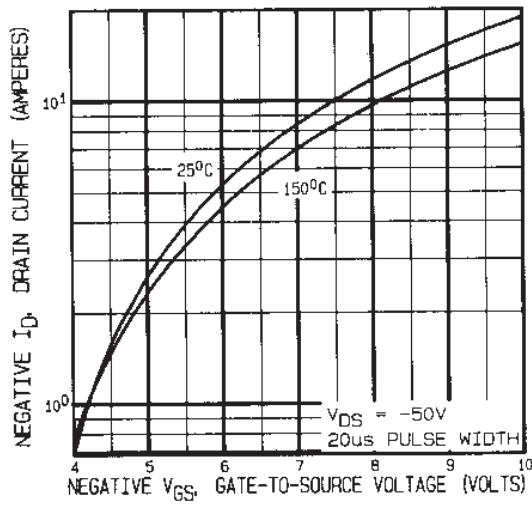
For footnotes refer to the last page



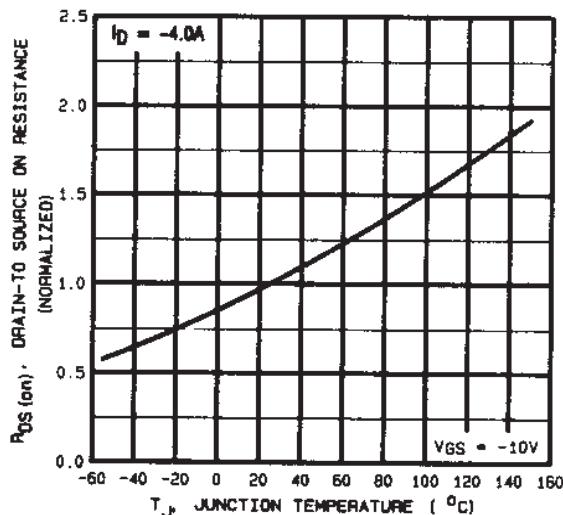
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics



**Fig 3.** Typical Transfer Characteristics



**Fig 4.** Normalized On-Resistance  
Vs. Temperature

## IRFF9120

International  
**IR** Rectifier  
 AN INFINEON TECHNOLOGIES COMPANY

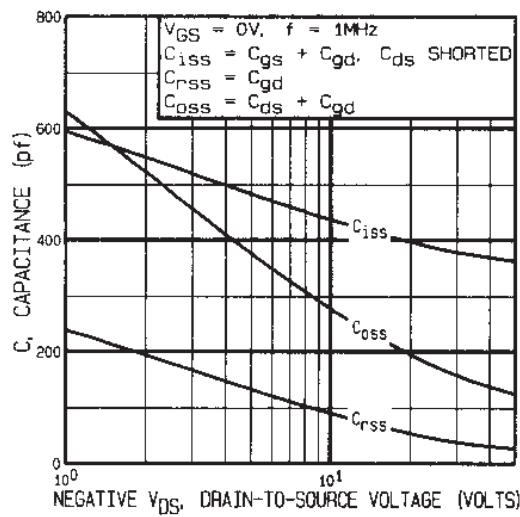


Fig 5. Typical Capacitance Vs.  
 Drain-to-Source Voltage

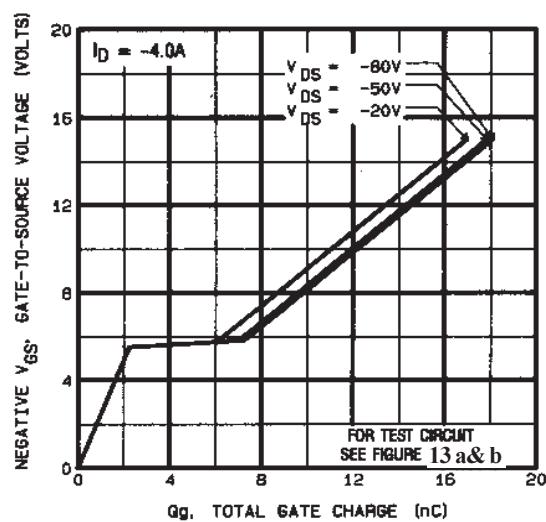


Fig 6. Typical Gate Charge Vs.  
 Gate-to-Source Voltage

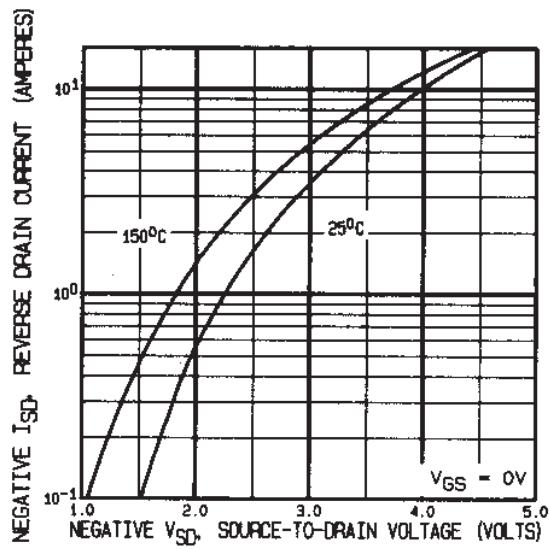


Fig 7. Typical Source-Drain Diode  
 Forward Voltage

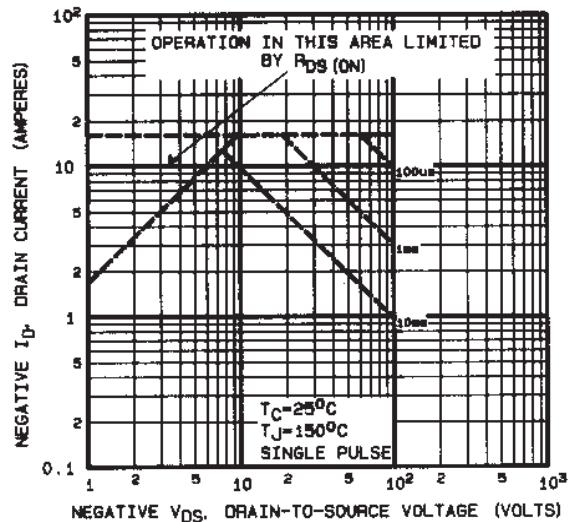
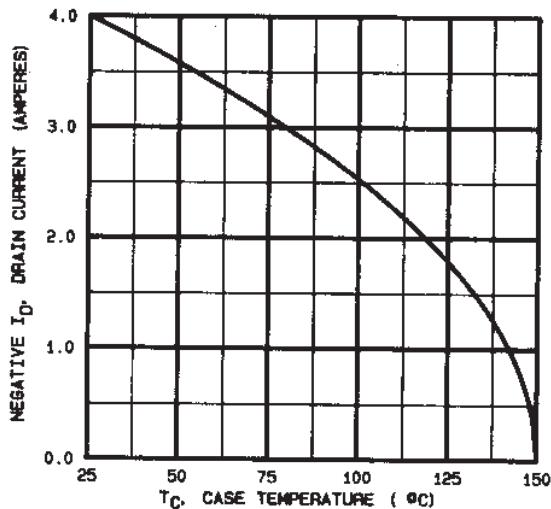
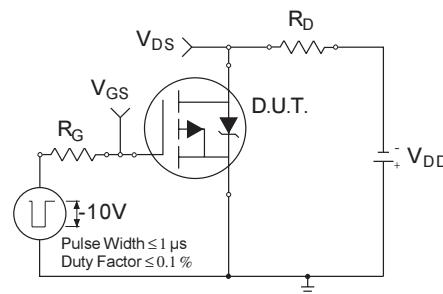


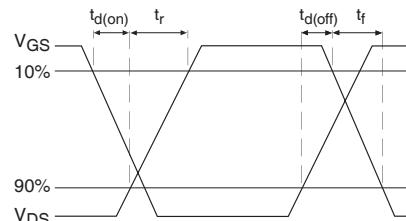
Fig 8. Maximum Safe Operating Area



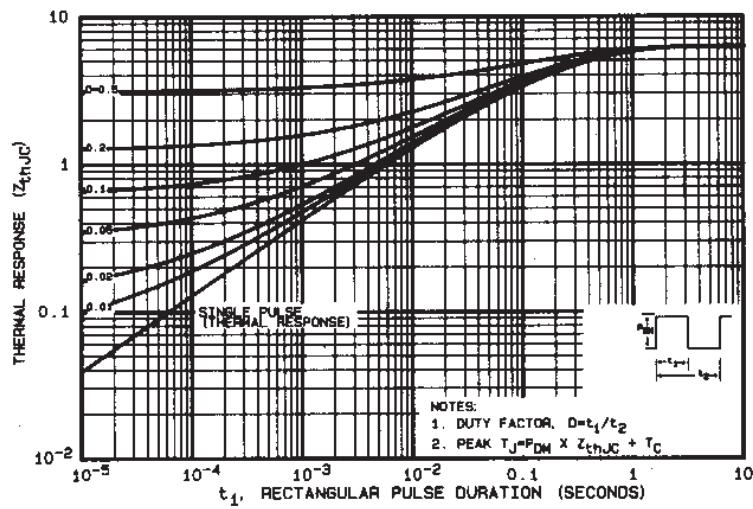
**Fig 9.** Maximum Drain Current Vs.  
Case Temperature



**Fig 10a.** Switching Time Test Circuit

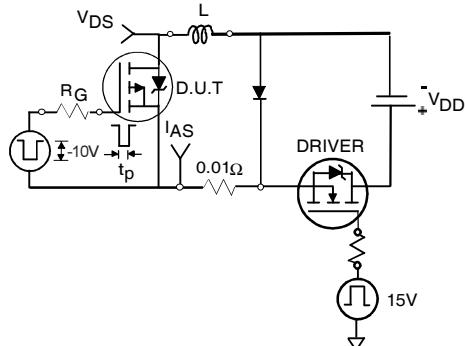


**Fig 10b.** Switching Time Waveforms

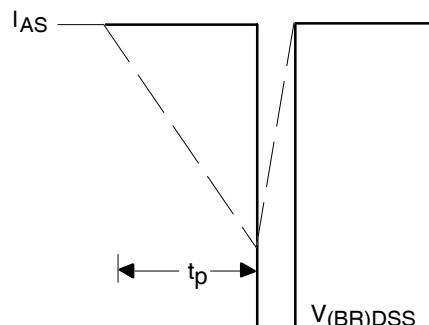


**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

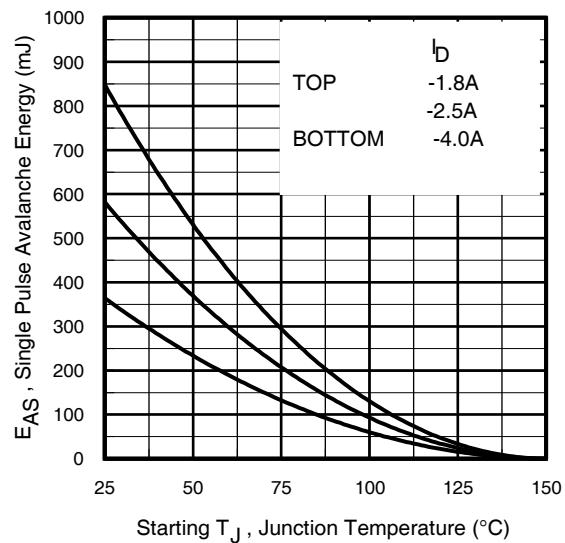
## IRFF9120



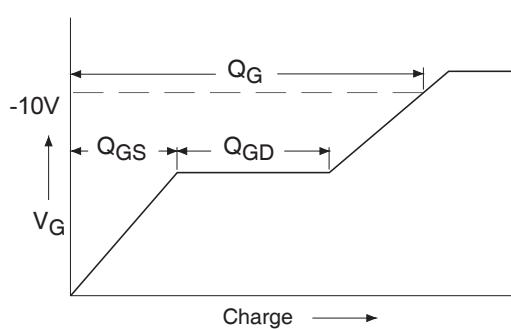
**Fig 12a.** Unclamped Inductive Test Circuit



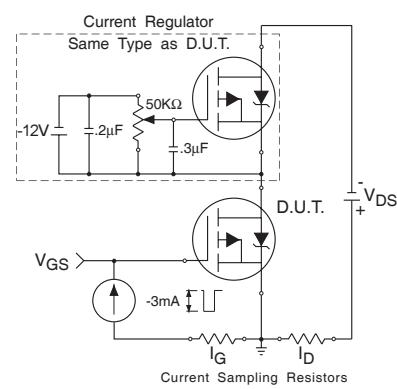
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13a.** Basic Gate Charge Waveform

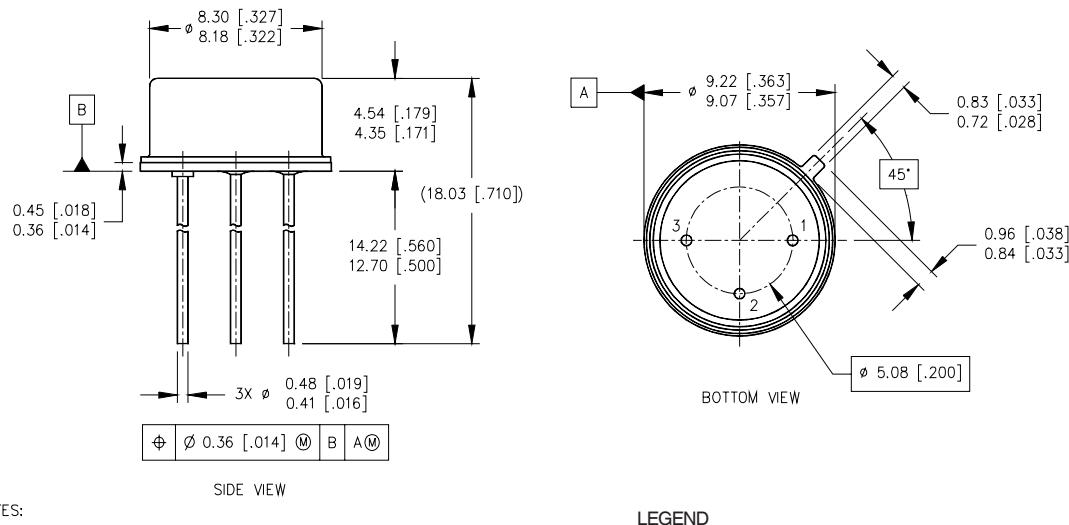


**Fig 13b.** Gate Charge Test Circuit

### Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = -25V$ , starting  $T_J = 25^\circ C$ , Peak  $I_L = -4.0A$ ,  $L = 45.5mH$ ,  $V_{GS} = 10V$
- ③  $I_{SD} \leq -4.0A$ ,  $dI/dt \leq -110A/\mu s$ ,  $V_{DD} \leq -100V$ ,  $T_J \leq 150^\circ C$   
Suggested  $R_G = 7.5 \Omega$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$

### Case Outline and Dimensions —TO-205AF (TO-39)



International  
**IR** Rectifier

AN INFINEON TECHNOLOGIES COMPANY

**IR WORLD HEADQUARTERS:** 101 N. Sepulveda Blvd., El Segundo, California 90245, USA Tel: (310) 252-7105  
**IR LEOMINSTER :** 205 Crawford St., Leominster, Massachusetts 01453, USA Tel: (978) 534-5776

Visit us at [www.irf.com](http://www.irf.com) for sales contact information.  
*Data and specifications subject to change without notice. 10/2015*